Krypton solutions
RS-485 HALF DUPLEX ESD SURGE
ALL ARTWORK LAYERS VIEWED FROM TOP

BOARD NAME: Krypton solutions
BOARD REV: A
KSID: 16093
JOB NUMBER: 126503

LAYER DESCRIPTION: LAYER X TOP X SIDE

ART FILM - TOP
<table>
<thead>
<tr>
<th>KRIPTON SOLUTIONS</th>
<th>BOARD NAME:</th>
<th>RS-485 HALF DUPLEX ESD SURGE</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>BOARD REV:</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td>KSID:</td>
<td>16093</td>
</tr>
<tr>
<td></td>
<td>JOB NUMBER:</td>
<td>126503</td>
</tr>
</tbody>
</table>

**ALL ARTWORK LAYERS VIEWED FROM TOP**

**LAYER DESCRIPTION:**

```plaintext
SOLDERMASK TOP
```

**JOB NUMBER:** 16093
RS-485 HALF DUPLEX ESD SURGE

ALL ARTWORK LAYERS VIEWED FROM TOP

126503

JOB NUMBER: 16093

KSID: A

BOARD REV:

GOLDERMAVX BBDDMX
RT FILM - SILK TOP

BOARD NAME: RS-485 HALF DUAL EX ESD SURGE

ALL ARTWORK LAYERS VIEWED FROM TOP

LAYER DESCRIPTION:

RS-485 TRANSIENT PROTECTION REV.A

Texas Instruments

Krypton Solutions
ART FILM - PMASK_TOP

126503

 JOB NUMBER:

16093

KSID:

A

ALL ARTWORK LAYERS VIEWED FROM TOP

PASTEMASK TOP

X X X X X

BOARD NAME:

RS-485 HALF DUPLEX ESD SURGE

BOARD REV:

A

KSID:

16093

JOB NUMBER:

126503

LAYER DESCRIPTION:

PASTEMASK
Krypton Solutions

BOARD NAME: RS-485 HALF DUPLEX ESD SURGE
ALL ARTWORK LAYERS VIEWED FROM TOP

BOARD REV: A
KSID: 16093
JOB NUMBER: 126503

LAYER DESCRIPTION: PASTEMASK BOTTOM
BOARD NAME: RS-485 HALF DUPLEX SURGE

ASSEMBLY DRAWING (TOP SIDE)
## Table 1: Design Information

<table>
<thead>
<tr>
<th>Layer</th>
<th>Description</th>
<th>Ref</th>
<th>Qty</th>
</tr>
</thead>
<tbody>
<tr>
<td>L1:</td>
<td>Copper 1/2 oz Plated 1.4 mil</td>
<td>0.3</td>
<td>9</td>
</tr>
<tr>
<td></td>
<td>Soldermask 0.8 mil 0.8 mil</td>
<td></td>
<td>12</td>
</tr>
<tr>
<td></td>
<td>Core 1.50 57.6 mil</td>
<td></td>
<td>4</td>
</tr>
<tr>
<td>L2:</td>
<td>Copper 1/2 oz Plated 1.4 mil</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>Soldermask 0.8 mil 0.8 mil</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>Core 1.50 57.6 mil</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>L3:</td>
<td>Copper 1/2 oz Plated 1.4 mil</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>Soldermask 0.8 mil 0.8 mil</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>Core 1.50 57.6 mil</td>
<td></td>
<td>4</td>
</tr>
</tbody>
</table>

**Fabrication Notes:**
- FAB SHOP MUST FOLLOW THE SOLDER MASK REVIEW LAYERS.
- DRILL CHART: TOP to BOTTOM
- BOARD NAME: RS-485 HALF DUPLEX ESD SURGE
- ALL ARTWORK LAYERS VIEWED FROM TOP
- BOARD SURFACE TREATMENT: IMMERSION TIN
- THIEVING ALLOWED: NO
- BOARD FINISH: NICKEL/GOLD (ENIG)
- THRU-HOLE VIA TREATMENT: ORGANIC (OSP)
- VIA FILL USING NON-CONDUCTIVE EPOXY: NO
- VENDOR DATE CODE, UL, LOGO: IN AN OPEN AREA
- OTHER: CUSTOMER SIZE

**References:**
- Reference to tables and figures is included in the diagram.
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